

MA27D29

Silicon epitaxial planar type

For super high speed switching

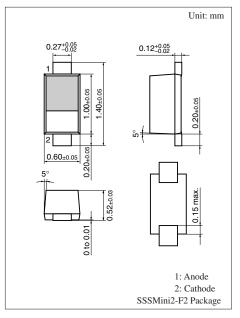
■ Features

- Low forward voltage: $V_F < 0.42 \text{ V}$ (at $I_F = 100 \text{ mA}$)
- \bullet Optimum for high frequency rectification because of its short reverse recovery time $t_{rr}\,.$

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	30	V
Repetitive peak reverse voltage	V _{RRM}	30	V
Forward current (Average)	I _{F(AV)}	100	mA
Peak forward current	I_{FM}	200	mA
Non-repetitive peak forward	I _{FSM}	1	A
surge current *			
Junction temperature	T _j	125	°C
Storage temperature	T_{stg}	-55 to +125	°C

Note) *: The peak-to-peak value in one cycle of 50 Hz sine wave (non-repetitive)



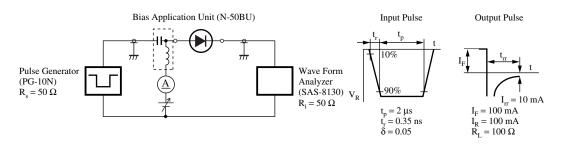
Marking Symbol: 8M

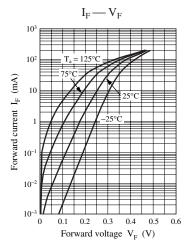
■ Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

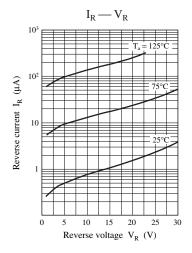
·	Parameter	Symbol	Conditions	Min	Тур	Max	Unit
•	Forward voltage	V_{F1}	$I_F = 10 \text{ mA}$		0.25	0.29	V
		V_{F2}	$I_F = 100 \text{ mA}$		0.39	0.42	V
www	.Reversescurrentom	I_{R1}	$V_R = 10 \text{ V}$			25	μΑ
		I_{R2}	$V_R = 30 \text{ V}$			120	μΑ
	Terminal capacitance	C_{t}	$V_R = 0 V, f = 1 MHz$		11		pF
,	Reverse recovery time *	t _{rr}	$I_F = I_R = 100 \text{ mA}$		1		ns
			$I_{rr} = 10 \text{ mA}, R_{L} = 100 \Omega$				

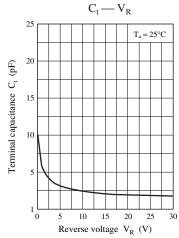
 $Note) \ 1. \ Measuring \ methods \ are \ based \ on \ JAPANESE \ INDUSTRIAL \ STANDARD \ JIS \ C \ 7031 \ measuring \ methods \ for \ diodes.$

- 2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
- 3. Absolute frequency of input and output is 250 MHz
- 4. *: t_{rr} measurement circuit









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